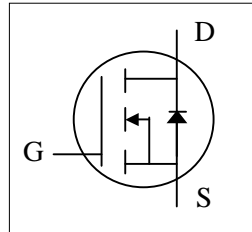




- ▼ Simple Drive Requirement
- ▼ Lower Gate Chage
- ▼ Fast Switching Characteristic
- ▼ RoHS Compliant & Halogen-Free

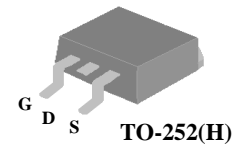
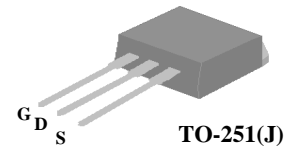


BV_{DSS}	90V
$R_{DS(ON)}$	240m Ω
I_D	7A

Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-252 package is widely preferred for commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters. The through-hole version (AP9995GJ) is available for low-profile applications.



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	90	V
V_{GS}	Gate-Source Voltage	+20	V
$I_D@T_c=25^\circ\text{C}$	Continuous Drain Current, V_{GS} @ 10V	7	A
$I_D@T_c=100^\circ\text{C}$	Continuous Drain Current, V_{GS} @ 10V	4.4	A
I_{DM}	Pulsed Drain Current ¹	15	A
$P_D@T_c=25^\circ\text{C}$	Total Power Dissipation	20.8	W
$P_D@T_A=25^\circ\text{C}$	Total Power Dissipation ³	2	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Value	Units
R_{thj-c}	Maximum Thermal Resistance, Junction-case	6.0	$^\circ\text{C}/\text{W}$
R_{thj-a}	Maximum Thermal Resistance, Junction-ambient (PCB mount) ³	62.5	$^\circ\text{C}/\text{W}$
R_{thj-a}	Maximum Thermal Resistance, Junction-ambient	110	$^\circ\text{C}/\text{W}$



AP9995GH/J-HF

Electrical Characteristics @ T_j=25°C (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	90	-	-	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =3A	-	-	240	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	2	-	5	V
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =3A	-	4	-	S
I _{DSS}	Drain-Source Leakage Current	V _{DS} =72V, V _{GS} =0V	-	-	25	uA
I _{GSS}	Gate-Source Leakage	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Q _g	Total Gate Charge	I _D =3A	-	8	12.8	nC
Q _{gs}	Gate-Source Charge	V _{DS} =72V	-	3	-	nC
Q _{gd}	Gate-Drain ("Miller") Charge	V _{GS} =10V	-	3.3	-	nC
t _{d(on)}	Turn-on Delay Time	V _{DS} =45V	-	8	-	ns
t _r	Rise Time	I _D =3A	-	7.5	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =3.3Ω	-	10.5	-	ns
t _f	Fall Time	V _{GS} =10V	-	3	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	360	576	pF
C _{oss}	Output Capacitance	V _{DS} =25V	-	40	-	pF
C _{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	30	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{SD}	Forward On Voltage ²	I _S =3A, V _{GS} =0V	-	-	1.3	V
t _{rr}	Reverse Recovery Time	I _S =3A, V _{GS} =0V,	-	40	-	ns
Q _{rr}	Reverse Recovery Charge	di/dt=100A/μs	-	85	-	nC

Notes:

1. Pulse width limited by Max. junction temperature.
2. Pulse test
3. Surface mounted on 1 in² copper pad of FR4 board

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

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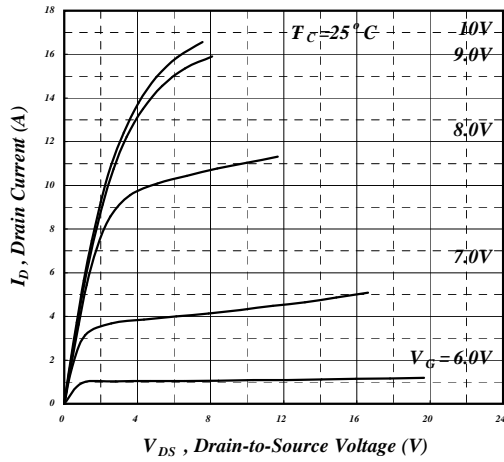


Fig 1. Typical Output Characteristics

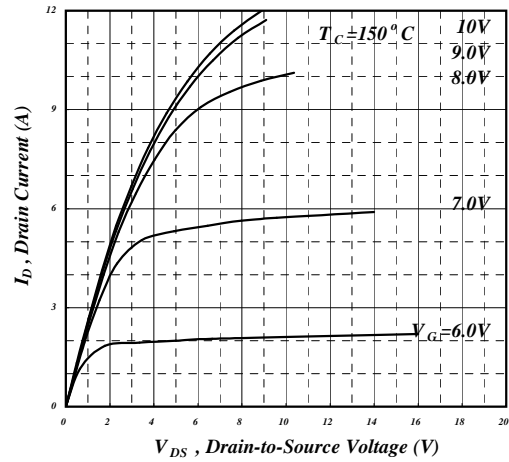


Fig 2. Typical Output Characteristics

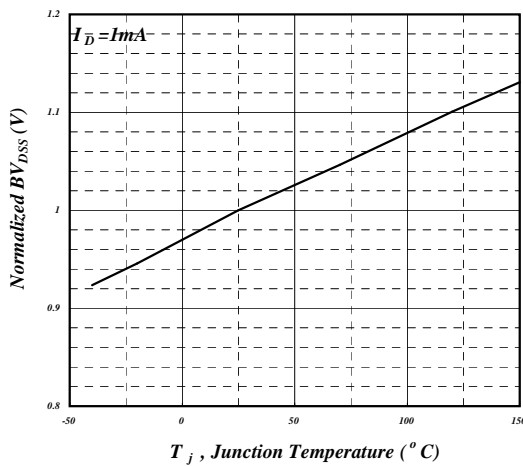


Fig 3. Normalized BV_{DSS} v.s. Junction Temperature

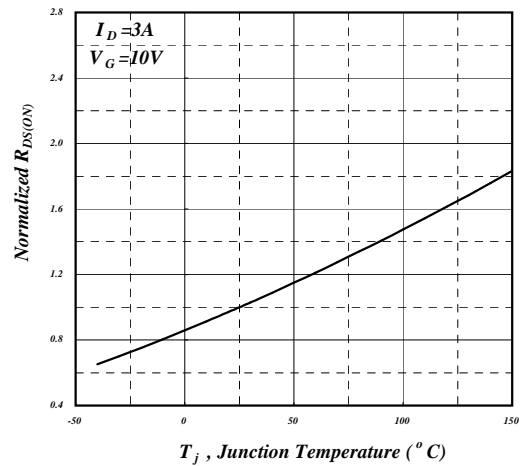


Fig 4. Normalized On-Resistance v.s. Junction Temperature

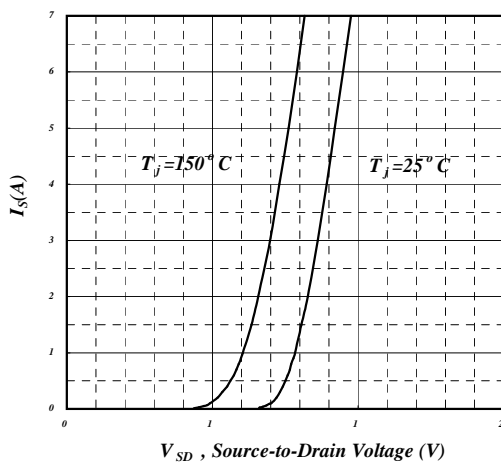


Fig 5. Forward Characteristic of Reverse Diode

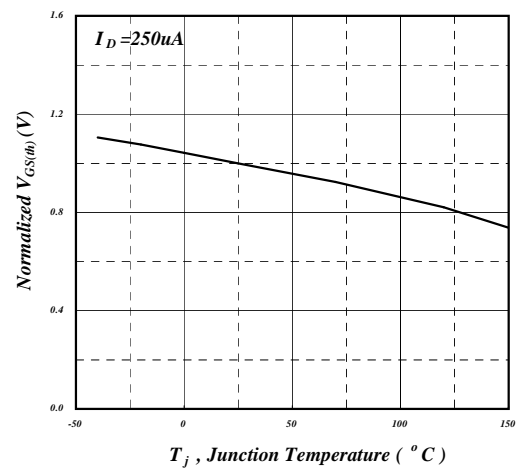


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

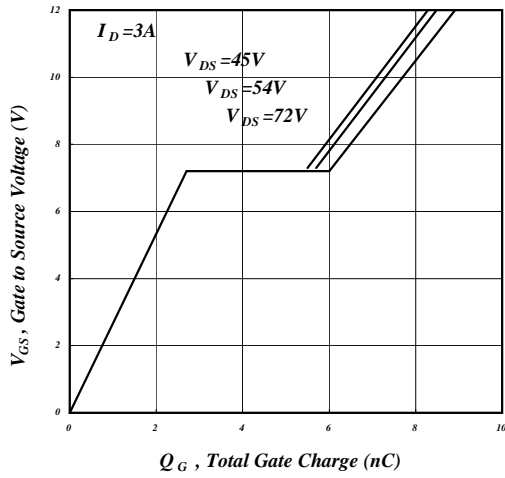


Fig 7. Gate Charge Characteristics

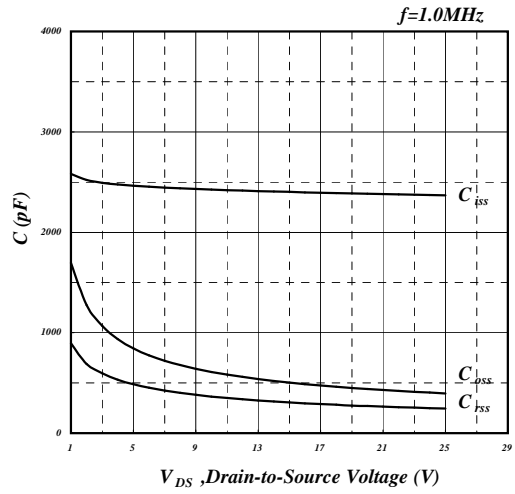


Fig 8. Typical Capacitance Characteristics

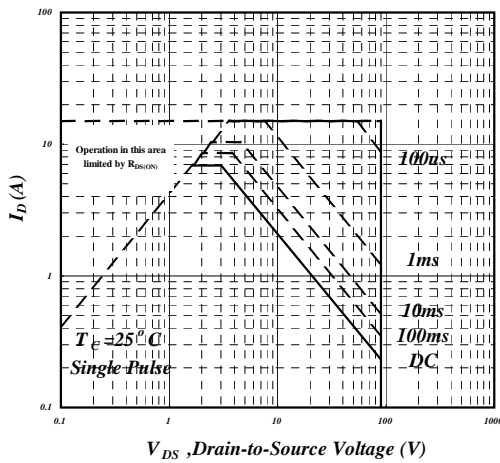


Fig 9. Maximum Safe Operating Area

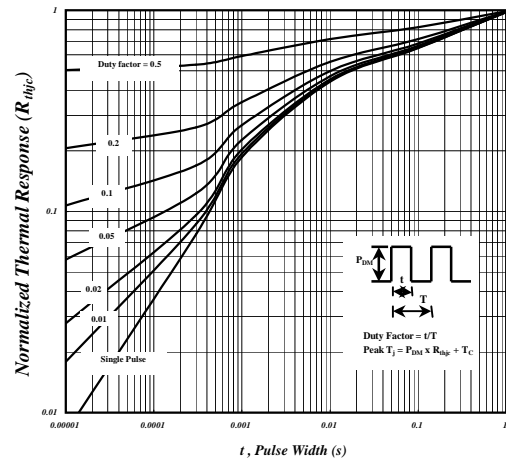


Fig 10. Effective Transient Thermal Impedance

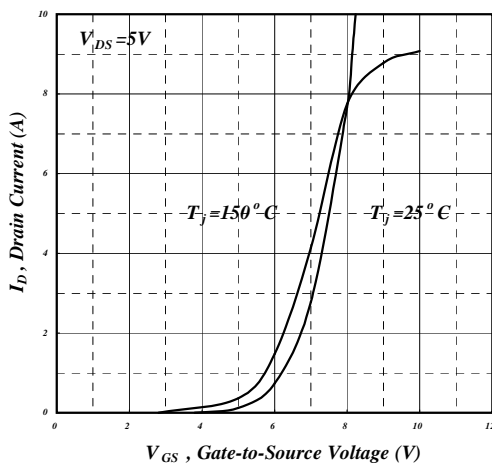


Fig 11. Transfer Characteristics

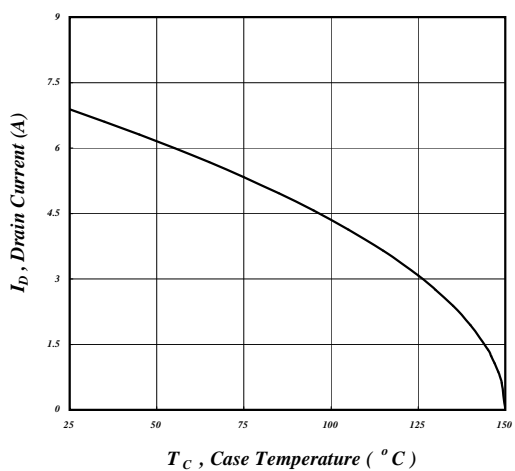


Fig 12. Maximum Continuous Drain Current v.s. Case Temperature